



# Product Change Notification

**Change Notification #:** 117339 - 00  
**Change Title:** Intel® Server System S9248WK1HLC,  
PCN 117339-00, Product Material,  
M.2 Heatsink - thermal gap filler  
**Date of Publication:** December 16, 2019

## Key Characteristics of the Change:

Product Material

## Forecasted Key Milestones:

<b>Date Customer Must be Ready to Receive Post-Conversion Material:*</b>	December 31, 2019
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\* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

## Description of Change to the Customer:

Intel has upgraded the thermal gap filler material used on the M.2 heatsinks. The improved thermal material has lower thermal resistance even in a low pressure. The new thermal gap filler is the same black color and form as the previous material.

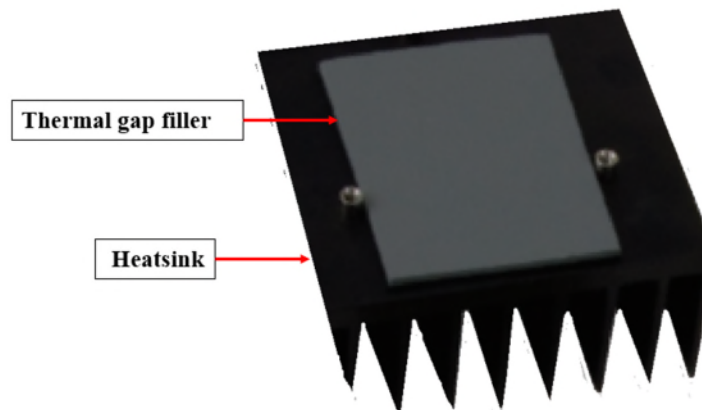


Figure 1. Thermal gap filler on heatsink

## Customer Impact of Change and Recommended Action:

Intel does not expect any other impact to customers from these changes described but encourages customers to understand the change and determine the impact on their applications. Intel has not shipped any previous M.2 heatsink.

### **Products Affected / Intel Ordering Codes:**

<b>Product Code</b>	<b>MM#</b>	<b>Pre Change TA</b>	<b>Post Change TA</b>
S9248WK1HLC	999D9T	K20899-007	K20899-008

### **PCN Revision History:**

**Date of Revision:**

December 16, 2019

**Revision Number:**

00

**Reason:**

Originally Published PCN



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**Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.**

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